

8th Workshop on Metallization & Interconnection for c-Si solar Cells (MIW 2019)

Topic 5:

Statement: 'Space between cells is so 2018! In the future all modules will have 100 % active area'

Moderators:

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Topic 5:

- Major driver is high power output and cost per Wp
- Getting closer to 100% is a trend but full square mono wafers are not expected in the near future (cost)
- Increasing active area by packing up cells is much more important than bifaciality effect for spacing
- Shingling is the best approach to increase power density
- Moving from standard to half to shingle increases power output 15Wp each step
- The market is starting to get confidence in shingling technology
- Target is 400Wp for 1,6 sqm panel

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Topic 5:

- Other interconnection techniques (back contact, smart wire) are improving power density compared to standard stringing
- For niche markets aesthetics can be dominant bringing to other solutions

Modified initial statement after discussion:

‘Space between cells is so 2018! In the future standard modules will be closer to 100 % active area’

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THANK YOU!